



Packaging semiconductor / Back-end Process Technician - W/M

Ref : 2022-MT1

Do you want to participate in a project that boosts the imaging industry ?

Company

SILINA is a **deeptech startup** that has raised several million euros to give birth to the **new generation of vision systems**, thanks to a **disruptive technology** that enables to curve imaging sensors (e.g CMOS) at industrial scale.

This **major innovation** in the semiconductor field aims to become the **new standard of the imaging industry**. It brings **superior image and detection quality** to vision systems & cameras in multiple imaging markets, with the added bonus of **reducing the weight, volume and cost** of these systems. SILINA offers its client **turnkey sensor curving solutions**. Having already attracted major players in aerospace, smartphones, automotive, virtual reality ... it now enters its manufacturing phase. SILINA needs you in order to ensure the Quality Assurance and Quality Control within the company.

We are recruiting a **Packaging Semiconductor / Back-end Process Technician** as a permanent position (CDI) in our facilities in Gardanne (13).

Job Summary

You are responsible for the implementation of manufacturing processes, inspection, and testing of components, especially curved image sensors. You are in strong interaction with the production manager, the technology team and the cleanroom operators. Your technical expertise in the packaging of image sensors (including Datacon pick-and-place and die bonding machines) allows you to produce and propose process improvements. You work in an ISO5-8 clean room environment and will be trained in several state-of-the-art equipment.

Your Missions

- Implement manufacturing, inspection, and component testing procedures,
- Implement automated packaging process (pick-and-place, bonding, wire bonding, deposit of cover glass) in order to guarantee a repeatable process and to increase the production rate,
- Support engineers and technicians on grinding and dicing steps,
- Perform environmental tests (thermal, humidity, mechanical) on components,
- Report on manufacturing results, metrology tests, environmental tests, etc.
- Handle samples during all the steps from the receipt of wafers to the shipment of end products to the customer,
- Be active to propose improvement solutions through constant feedback to the production and technology team

Your Profile

- Bac +2/3 in physics, chemistry, materials, physical measurements, or processes
- You have a minimum of 5 years experience on the back-end semiconductor processes of image sensors,
- You master pick-and-place and die bonding machines (eg DATACON 2200)
- Have knowledge of statistical process control (SPC), silicon etching (RIE etching, ...) or chemical decontamination and cleaning would be a plus,
- You are rigorous and pay attention to details,
- You are curious about new techniques, and can appreciate diverse missions as well as serial production needs,
- You show a strong autonomy and hands-on skills
- You demonstrated good soft skills in team work



Job Highlights

- Diversified activities
- Technical challenges
- Disruptive technology

Contact : pierre.delcroix@silina.io , wilfried.jahn@silina.io

